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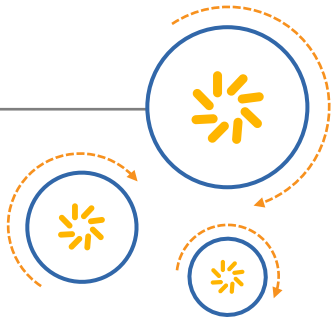

SAW components

SAW RF filter for base station

Series/type:	B5114
Ordering code:	B39781B5114U410
Date:	June 08, 2016
Version:	2.4

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RF360 Europe GmbH, Anzinger Str. 13, München, Germany

SAW components

SAW RF filter for base station

Series/type:	B5114
Ordering code:	B39781B5114U410
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Table of contents

1 Application

- RF filter for base station
- Unbalanced to unbalanced operation
- Low amplitude ripple
- Usable pass band 11 MHz
- No matching required for operation at 50 Ω

2 Features

- Package code DCC6C
- Package size 3.0±0.1 mm × 3.0±0.1 mm
- Package height 1.1±0.125 mm
- Approximate weight 0.04 g
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au plated terminals
- Lead free soldering compatible with J-STD20C
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 1 (MSL1)

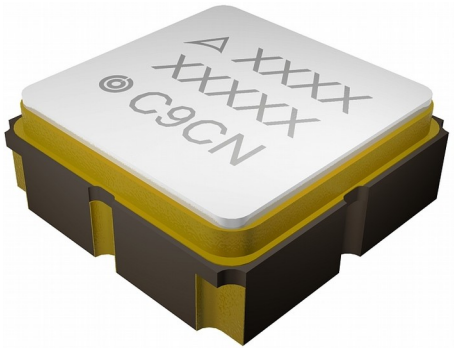


Figure 1: Picture of component with example of product marking.

3 Package

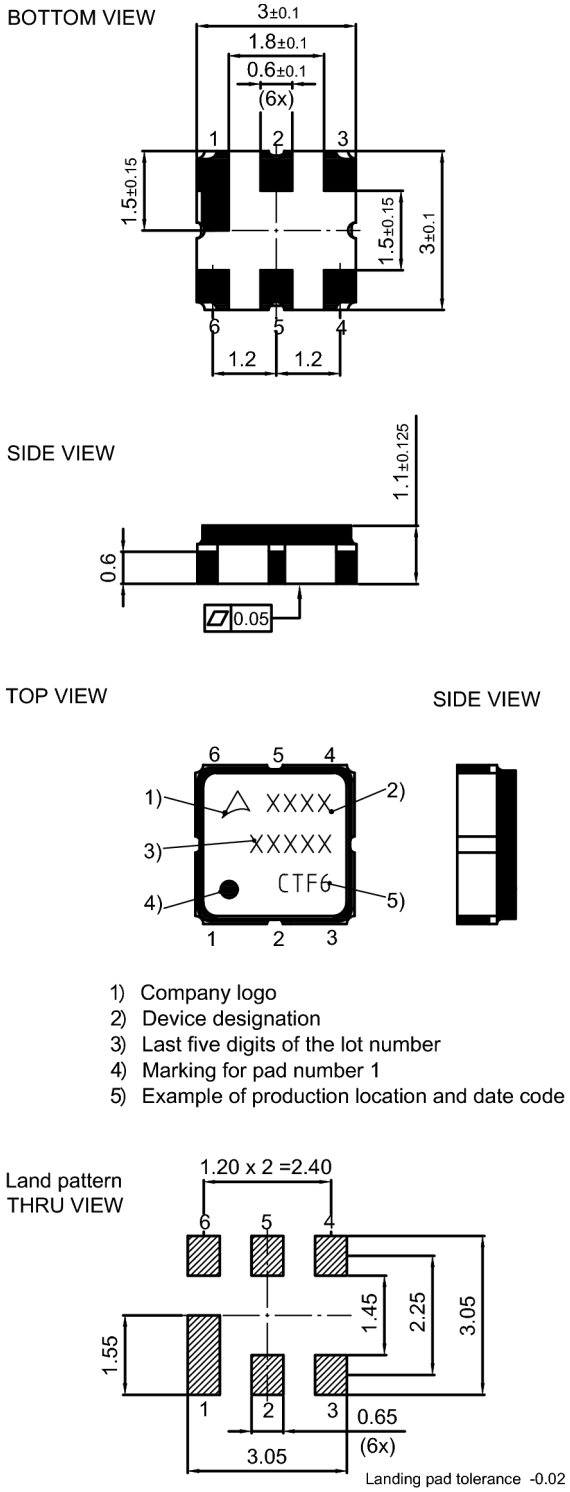


Figure 2: Drawing of package. See Sec. Package information (p. 17).

4 Pin configuration

- 2 Input
- 5 Output
- 1, 3, 4, 6 Ground

5 Matching circuit

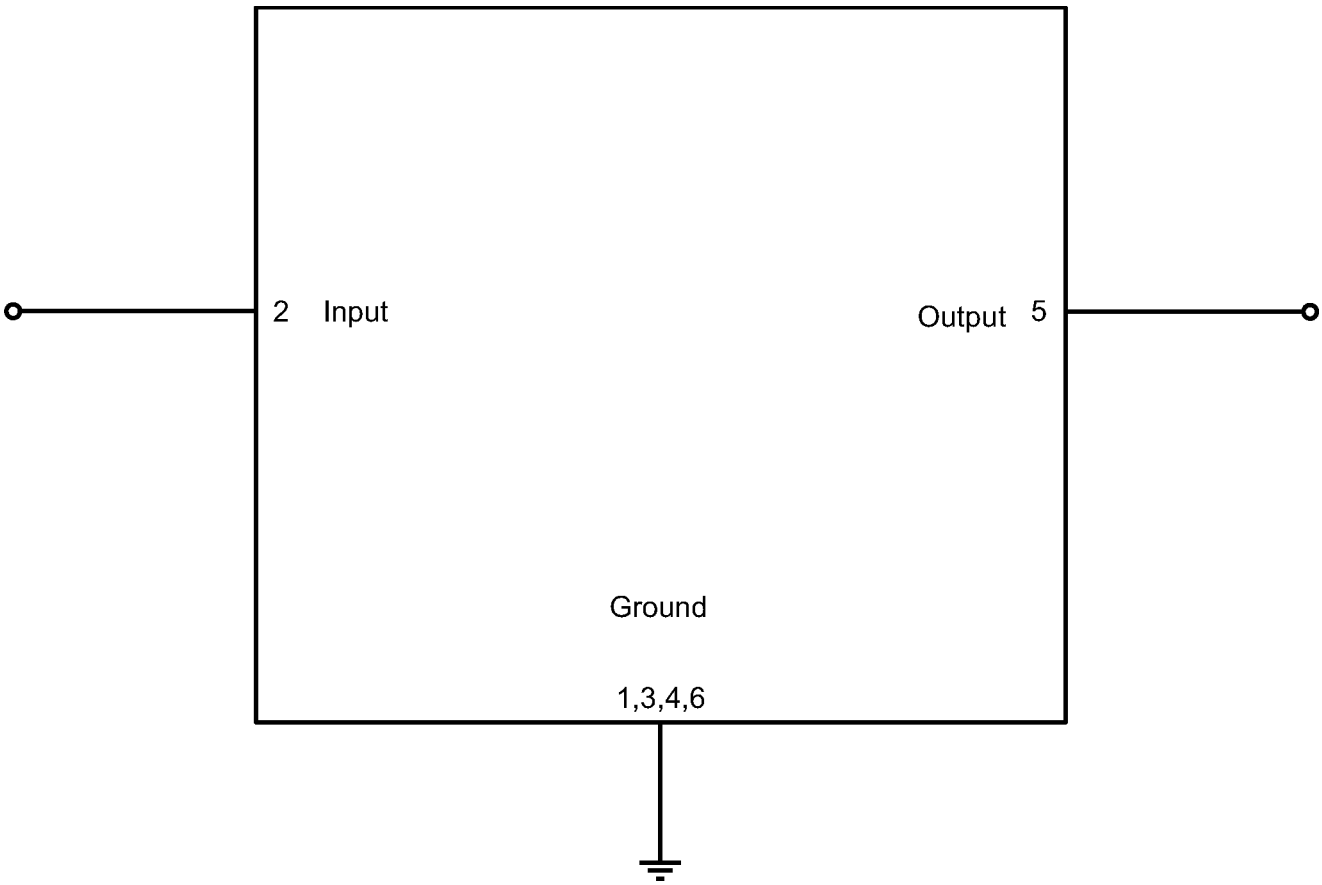


Figure 3: Schematic of matching circuit. No external matching components required.

6 Characteristics

Temperature range for specification T_{SPEC} = −40 °C ... +85 °C
Input terminating impedance Z_{IN} = 50 Ω
Output terminating impedance Z_{OUT} = 50 Ω

Characteristics				min. for T_{SPEC}	typ. @+25 °C	max. for T_{SPEC}	
Center frequency			f_C	—	781.5	—	MHz
Maximum insertion attenuation			α_{max}				
	776 ... 787	MHz		—	1.6	2.5	dB
Amplitude ripple (p-p)			$\Delta\alpha$				
	776 ... 787	MHz		—	0.6	1.5	dB
Amplitude ripple (in any segment of 5 MHz)			$\Delta\alpha$				
	776 ... 787	MHz		—	0.5	0.6	dB
Variation of group delay			$\Delta\tau_{var}$				
	776 ... 787	MHz		—	48	70	ns
Average group delay			$\Delta\tau_{avg}$				
	776 ... 787	MHz		—	35	70	ns
Maximum VSWR			$VSWR_{max}$				
@ input port	776 ... 787	MHz		—	1.3	1.9	
@ output port	776 ... 787	MHz		—	1.3	1.9	
Minimum attenuation			α_{min}				
	54 ... 700	MHz		35	40	—	dB
	700 ... 746	MHz		20	30	—	dB
	746 ... 757	MHz		20	28	—	dB
	758 ... 765	MHz		9	23	—	dB
	851 ... 894	MHz		30	44	—	dB
	894 ... 1250	MHz		28	35	—	dB
	1250 ... 2050	MHz		35	50	—	dB
	2050 ... 3800	MHz		10	13	—	dB

SAW RF filter for base station 781.5

Data sheet

Temperature range for specification	T_{SPEC}	= −40 °C ... +105 °C
Input terminating impedance	Z_{IN}	= 50 Ω
Output terminating impedance	Z_{OUT}	= 50 Ω

Characteristics				min. for T_{SPEC}	typ. @+25 °C	max. for T_{SPEC}	
Center frequency			f_C	—	781.5	—	MHz
Maximum insertion attenuation			α_{max}				
	776 ... 787	MHz		—	1.6	2.6	dB
Amplitude ripple (p-p)			$\Delta\alpha$				
	776 ... 787	MHz		—	0.6	1.6	dB
Amplitude ripple (in any segment of 5 MHz)			$\Delta\alpha$				
	776 ... 787	MHz		—	0.5	0.6	dB
Variation of group delay			$\Delta\tau_{var}$				
	776 ... 787	MHz		—	48	80	ns
Average group delay			$\Delta\tau_{avg}$				
	776 ... 787	MHz		—	35	80	ns
Maximum VSWR			$VSWR_{max}$				
@ input port	776 ... 787	MHz		—	1.3	1.9	
@ output port	776 ... 787	MHz		—	1.3	1.9	
Minimum attenuation			α_{min}				
	54 ... 700	MHz		35	40	—	dB
	700 ... 746	MHz		20	30	—	dB
	746 ... 757	MHz		20	28	—	dB
	758 ... 765	MHz		5	23	—	dB
	851 ... 894	MHz		30	44	—	dB
	894 ... 1250	MHz		28	35	—	dB
	1250 ... 2050	MHz		35	50	—	dB
	2050 ... 3800	MHz		10	13	—	dB

7 Maximum ratings

Operable temperature	T_{OP} = −45 °C ... +125 °C	
Storage temperature	T_{STG} = −45 °C ... +125 °C	
ESD voltage		
	V_{ESD} [1)] = 100 V (max.)	Machine model.
	V_{ESD} [2)] = 275 V (max.)	Human body model.
Input power @ input port: 776 ... 787 MHz	P_{IN} = 15 dBm	Continuous wave for 5000 h @ 100 °C.

1) According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.
2) According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse.

8 Transmission coefficient

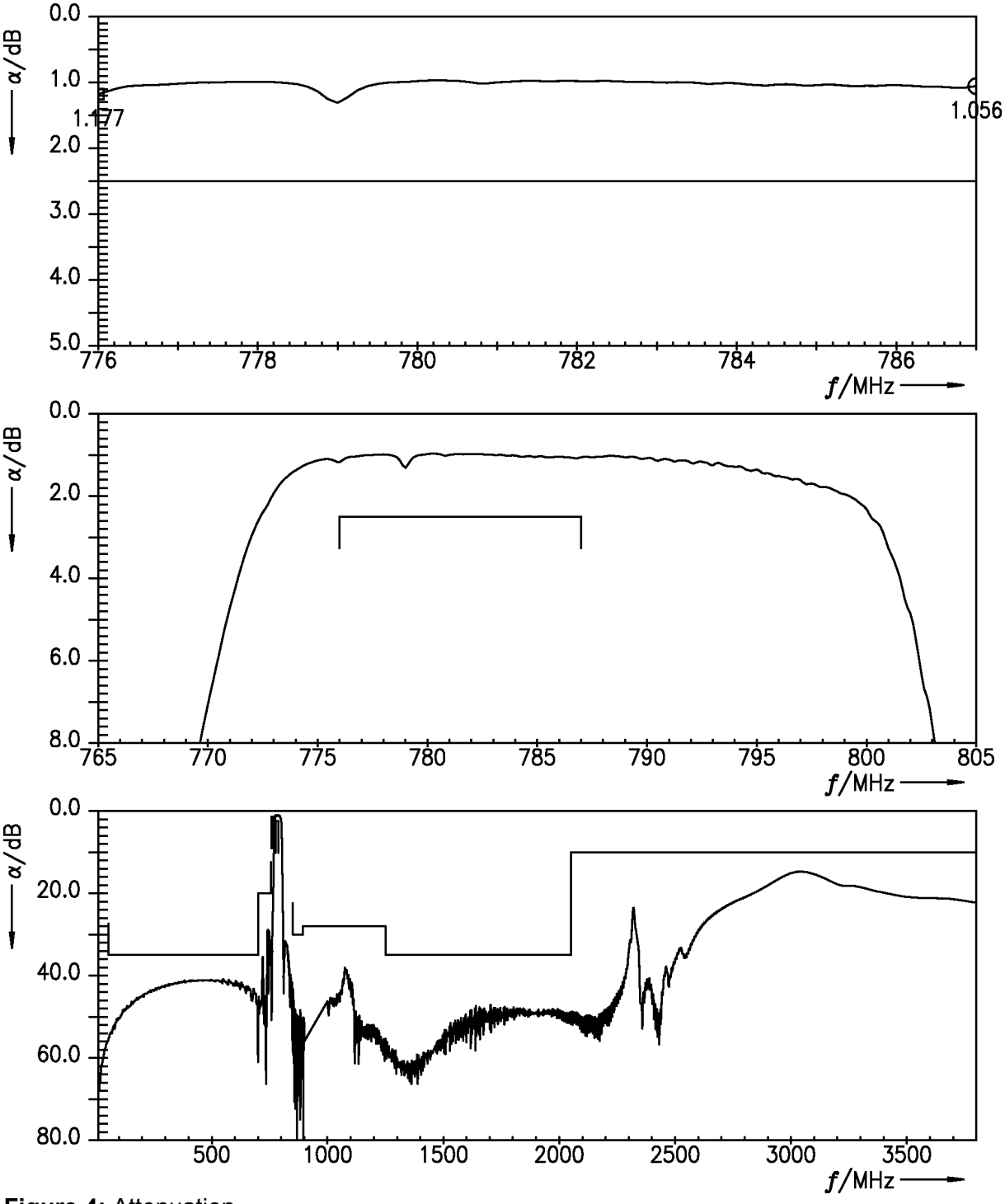


Figure 4: Attenuation.

9 Reflection coefficients

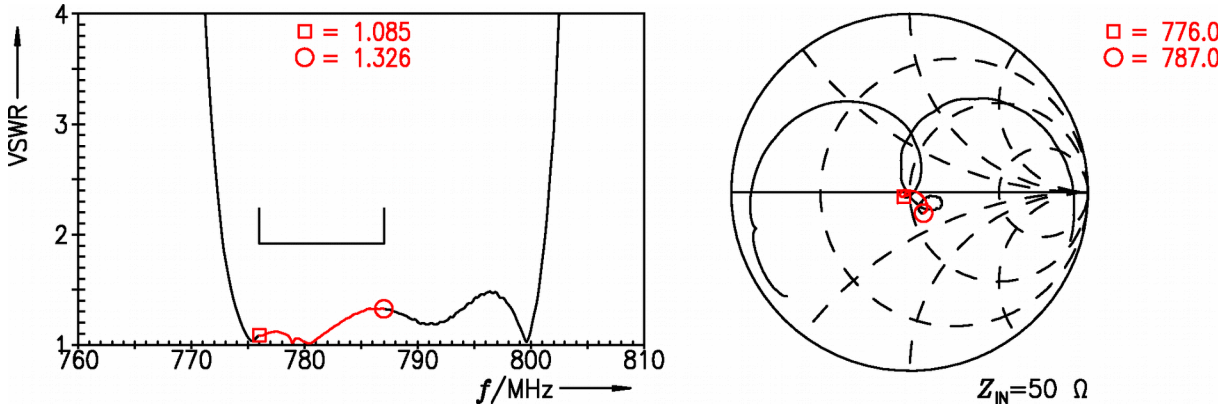


Figure 5: Reflection coefficient at IN port.

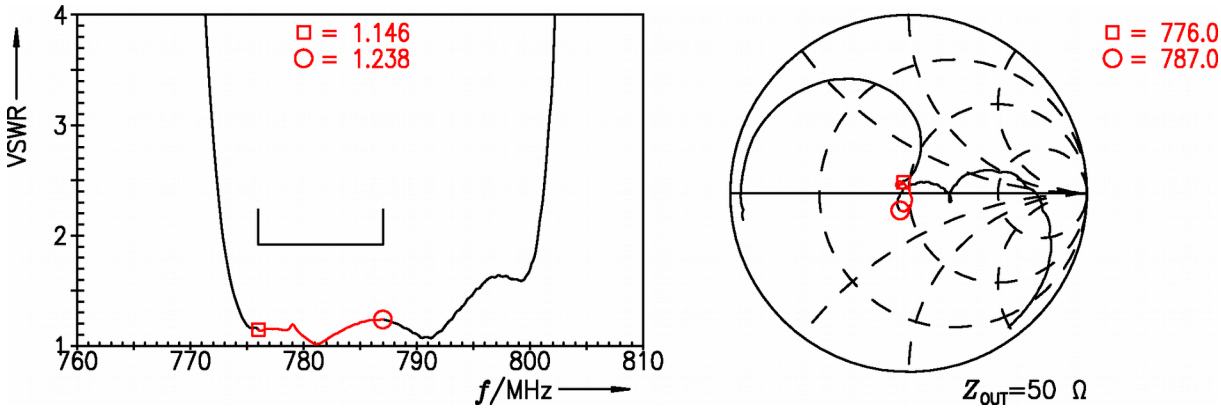


Figure 6: Reflection coefficient at OUT port.

10 Packing material

10.1 Tape

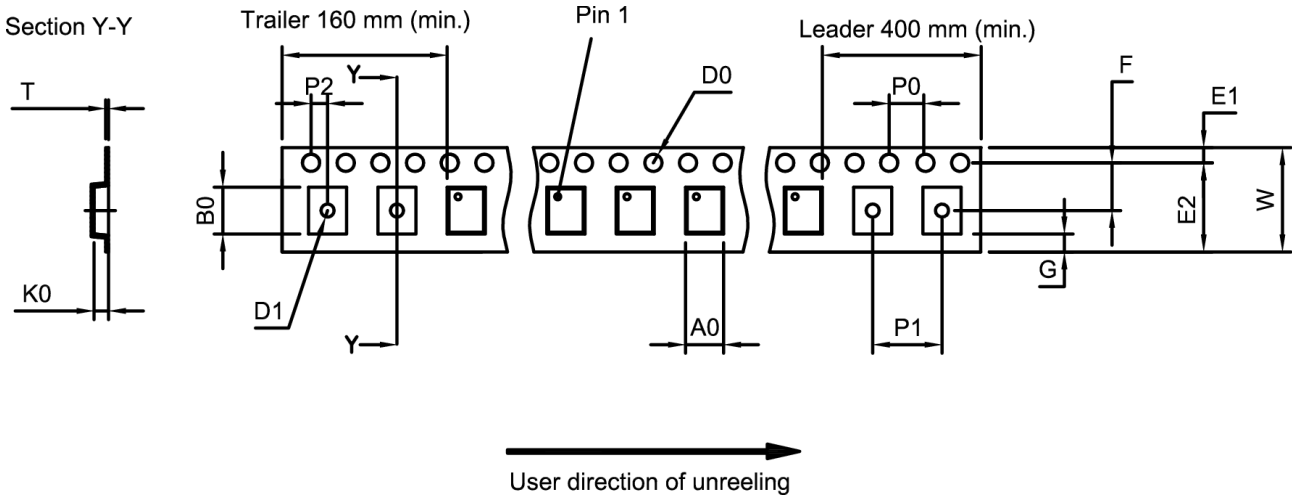


Figure 7: Drawing of tape (first-angle projection) with tape dimensions according to Table 1.

A_0	3.25±0.1 mm
B_0	3.3±0.1 mm
D_0	1.5+0.1/−0 mm
D_1	1.5 mm (min.)
E_1	1.75±0.1 mm

E_2	10.25 mm (min.)
F	5.5±0.05 mm
G	0.75 mm (min.)
K_0	1.5±0.1 mm
P_0	4.0±0.1 mm

P_1	4.0±0.1 mm
P_2	2.0±0.1 mm
T	0.2±0.05 mm
W	12.0+0.3/−0.1 mm

Table 1: Tape dimensions.

10.2 Reel with diameter of 180 mm

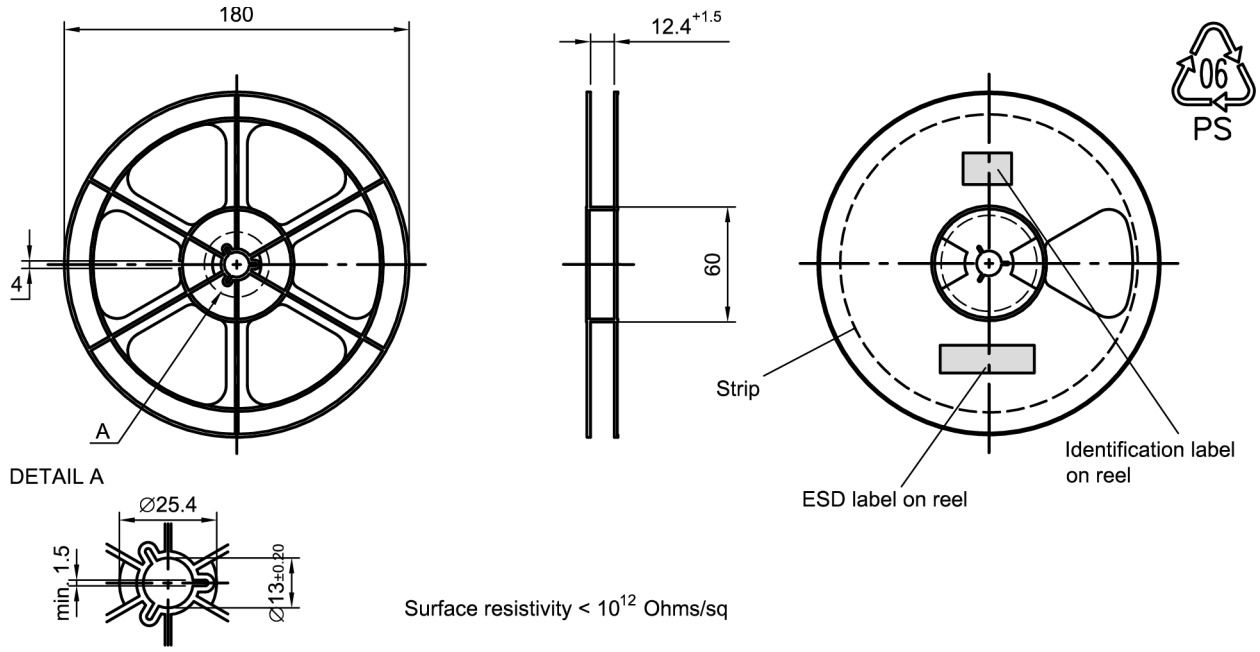
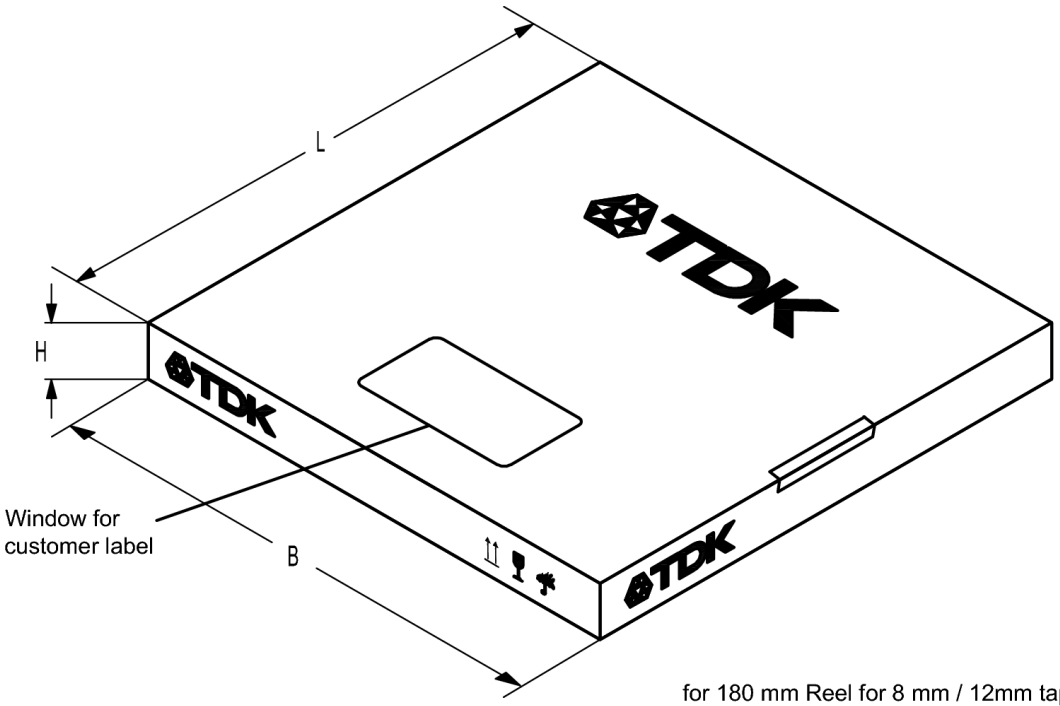


Figure 8: Drawing of reel (first-angle projection) with diameter of 180 mm.



Dimensions

L = 182
B = 185
H = 26

for 180 mm Reel for 8 mm / 12mm tape width
SMD packages

Figure 9: Drawing of folding box for reel with diameter of 180 mm.

10.3 Reel with diameter of 330 mm

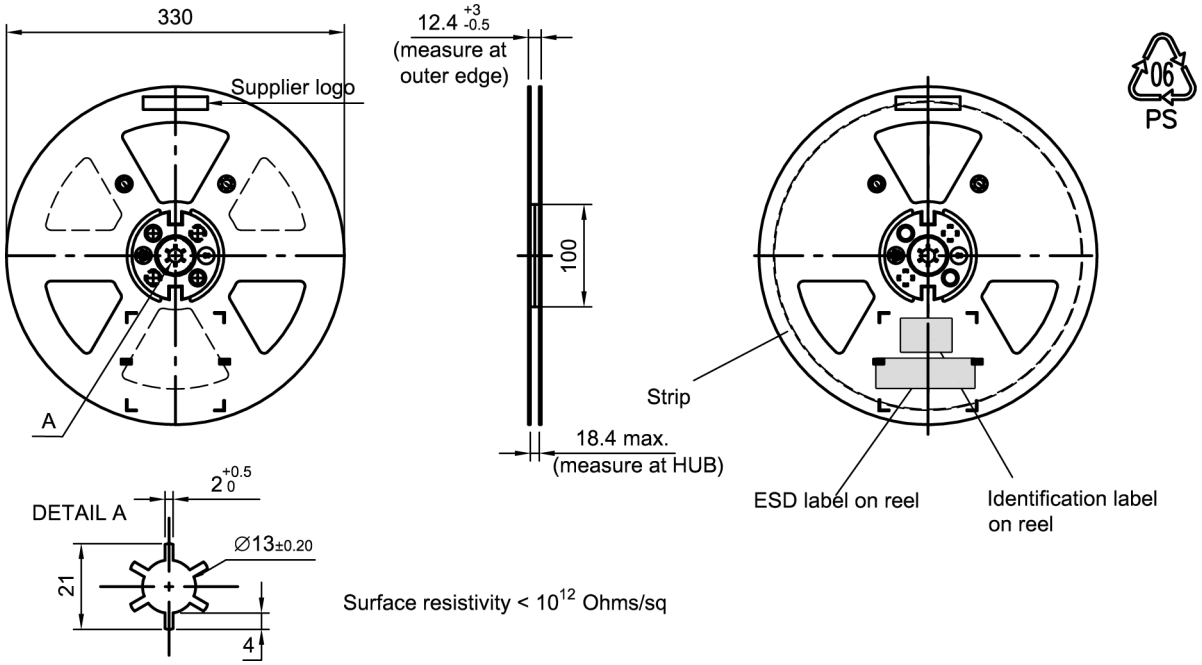
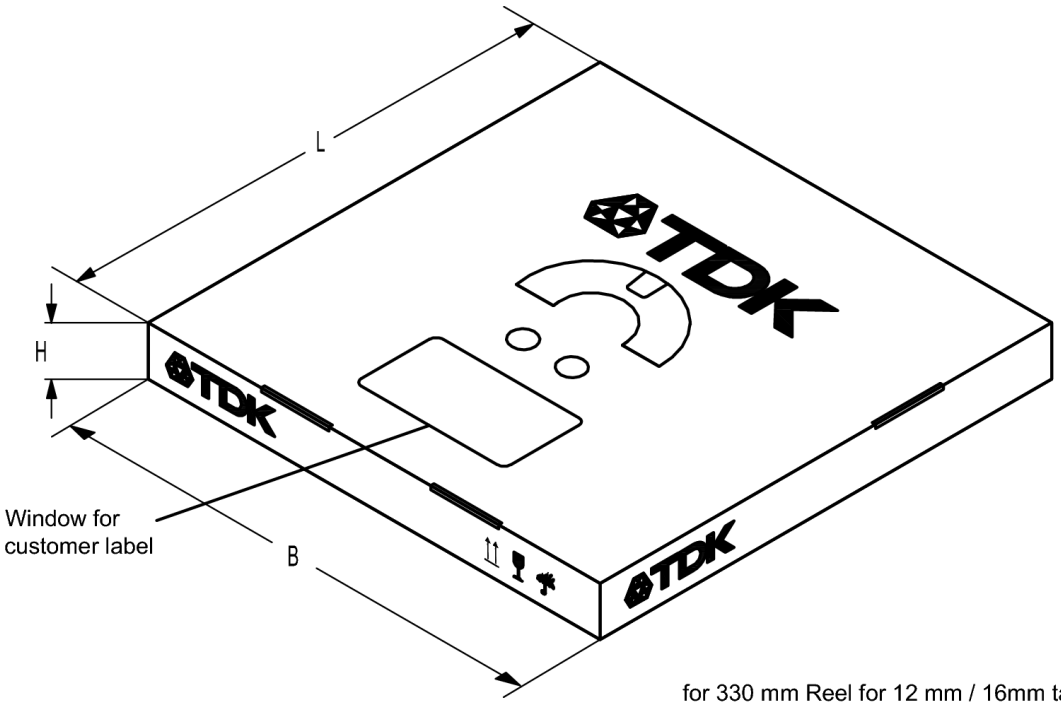


Figure 10: Drawing of reel (first-angle projection) with diameter of 330 mm.



Dimensions

L = 340
B = 340
H = 25

for 330 mm Reel for 12 mm / 16mm tape width
SMD packages

Figure 11: Drawing of folding box for reel with diameter of 330 mm.

11 Marking

Products are marked with device designation, lot number, as well as production location and date code.

- Device designation: The 4-character device designation of the ordering code is used for the marking.

  Example for 4-character device designation: B3xxxxB**1234**xxxx

- Lot number: The last 5 digits of the lot number are used for the marking.

  Example: **12345**

- Production location and date code: The production location is Wuxi (encoded in the first character 'C'). The production date code is encoded in the last three characters according to Table 2.

1st digit (day)					
Day	Code	Day	Code	Day	Code
1	1	11	A	21	M
2	2	12	B	22	N
3	3	13	C	23	P
4	4	14	D	24	R
5	5	15	E	25	S
6	6	16	F	26	T
7	7	17	H	27	U
8	8	18	J	28	V
9	9	19	K	29	W
10	0	20	L	30	X
				31	Z

2nd digit (year)			
Year	Code	Year	Code
2010	A	2022	P
2011	B	2023	R
2012	C	2024	S
2013	D	2025	T
2014	E	2026	U
2015	F	2027	V
2016	H	2028	W
2017	J	2029	X
2018	K	2030	Z
2019	L	2031	A
2020	M	2032	B
2021	N	and so on	

3rd digit (month)			
Month	Code	Month	Code
Jan	1	Jul	7
Feb	2	Aug	8
Mar	3	Sep	9
Apr	4	Oct	0
May	5	Nov	N
Jun	6	Dec	D

Table 2: Production date code.

Example of how to decode production location and date code:

Code: **C T F 6**

Location: C → Wuxi
Day: T → 26th
Year: F → 2015
Month: 6 → June

12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
T ≥ 255 °C	–
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

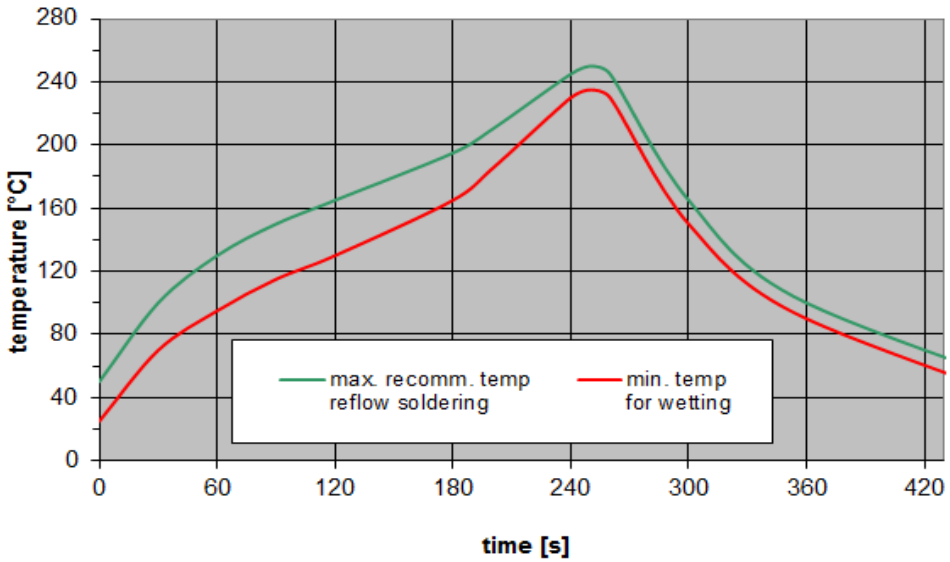


Figure 12: Recommended reflow profile for convection and infrared soldering – lead-free solder.

13 Annotations

13.1 Matching coils

See TDK inductor pdf-catalog http://www.tdk.co.jp/tefe02/coil.htm#aname1 and Data Library for circuit simulation http://www.tdk.co.jp/etvcl/index.htm.

13.2 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

13.3 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local EPCOS sales office.

14 Cautions and warnings

14.1 Display of ordering codes for EPCOS products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of EPCOS, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under **www.epcos.com/orderingcodes**.

14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

14.3 Moldability

Before using in overmolding environment, please contact your local EPCOS sales office.

14.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on EPCOS internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of EPCOS, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.

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2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified.** In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
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